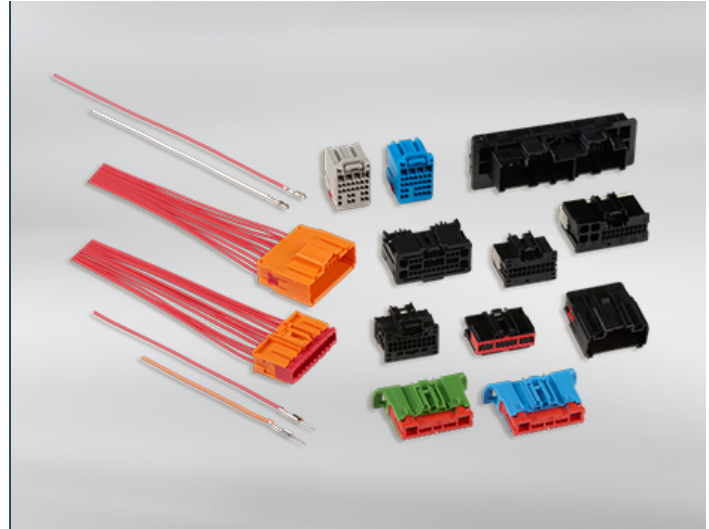


# INTRODUCING Generation Y CONNECTOR SYSTEM

- 2.2mm centerline pitch capable vs. typical 2.54mm to allow for greater density to reduce PCB costs and space savings
- Low mating force - up to 32 positions without a lever



The Generation Y portfolio of 0.64mm terminals, connectors, and headers, offers proven compact, low mating force connectivity solutions for a large range of signal applications. These connectors are available in various positions as well as hybrid connector designs.

## TARGETS

- Automotive

## APPLICATIONS

- Acceptable for multiple automotive applications for in-cabin to harsh environments with various base material and plating options
  - Powertrain
  - Body and Chassis
  - Infotainment and Interior
  - Safety
  - HVAC
  - ADAS

## PRODUCT FEATURES

- 2.2mm pin-to-pin pitch capability
- 0.64mm terminal system
- Current capacity: 10.5A (80°C)
- 0.13mm<sup>2</sup> to 0.75mm<sup>2</sup> wire range
- Wire-to-wire, wire-to-board, wire-to-device
- USCAR validated and present in Japanese OEMs
- USCAR Class 2 Vibration levels, Class 3 Temperature, and Class 3 Sealing
- Sealed and unsealed
- Through-hole, press-fit, and surface mount headers - available in vertical or right-angle orientations
- Independent secondary locking
- Hybrid connectors available with signal, power, and data

- Low mating force - up to 32 positions without a lever
- Capable for crimping to 18-26 AWG wire and dual crimp of 26 AWG

## KEY BENEFITS

- Sealed and unsealed connectors for use in cabin or engine applications
- Low engagement force contact allows for higher pin count with hand mate while meeting requirements of USCAR-25
- 2.2mm centerline pitch capable to allow for greater density to reduce PCB costs and space savings
- Configurable solutions that integrate data connections into low-voltage power and signal connectors
- Off-the-shelf or application specific designs available
- Header materials available for IR resistance and lead-free solder processing
- Geometries for front loaded TPA or side Locking ISL for terminal retention
- Header designs available with through-hole solder tails, surface mount tabs or press-fit compliant pin
- Header designs available in vertical or right-angle; without boardlocks
- Sealed and unsealed connectors exceed performance requirements of USCAR-2, -20, -21 and -25 connector design and ergonomic standards - ideal interconnect solution for heavy duty and harsh environment applications

## LEARN MORE

- [Landing Page](#)
- [Generation Y 68P Sealed Hybrid Inline Connector Landing Page](#)
- [Product Catalog](#)